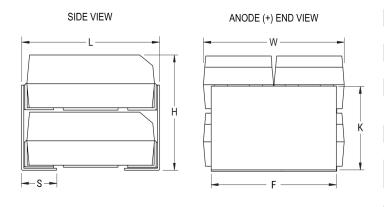


## TSP4B137M010BH6610H540

TSP, Tantalum, Polymer Tantalum, HRA, 130 uF, 20%, 10 VDC, 4B





Click here for the 3D model.

Dimensions	
Case Code	4B
L	4.1mm +/-0.38mm
W	6.1mm +/-0.2mm
Н	4.3mm +/-0.38mm
S	0.76mm +/-0.38mm
F	5.3mm +/-0.2mm
K	3.1mm +/-0.38mm

Packaging Specifications	
Packaging	Tray
Packaging Quantity	50

General Information	
Series	TSP
Dielectric	Polymer Tantalum
Style	Stacked Chip
Description	SMD, Polymer, KO, Stacks, High Reliability
Features	High Reliability
RoHS	No
Prop 65	▲ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov.
SCIP Number	30e82d35-b509-48ec-8c77-2d5ec01b3abc
Termination	Solder Coated
Termination (Stack)	Solder Coated
AEC-Q200	No
MSL	3

Specifications	
Capacitance	130 uF
Capacitance Tolerance	20%
Voltage DC	10 VDC (105C), 6.7 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	105°C
Dissipation Factor	8% 120Hz 25C
Failure Rate	B (0.1%/1000 Hrs)
Resistance	20 mOhms (100kHz 25C)
Leakage Current	132 uA (5min 25°C)
Testing and Reliability	10 Cycles Surge Current Testing At +25C +/- 5C After Voltage Aging

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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## >>KEMET(基美)